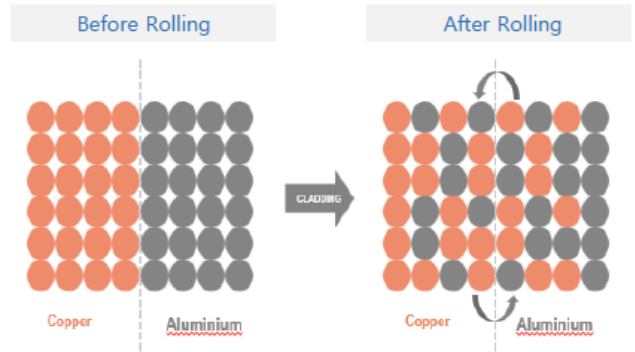
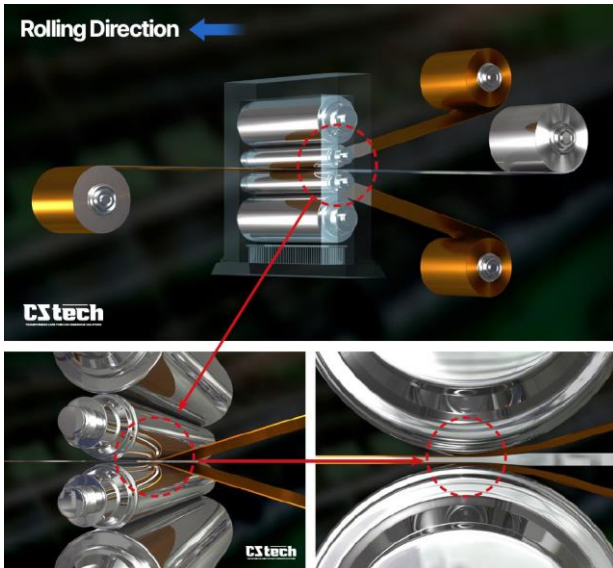


BIMETAL PLATES - BIMETALLIC SHEETS

Copper and Aluminium are conductors with different electric potential; direct contact between them generates effect of a galvanic cell which, in the presence of an electrolyte (typically simple humidity), starts a "battery effect" with consequent damage of the less noble metal getting worse the electrical characteristics. The interposition of a BIMETALLIC element Cu/Al between the two conductors avoids what above. The production process of this Metal Cladded Bimetallic Element (CLAD METAL refers to a material wherein the two different metals are bonded together with 'Rolling Process') molecularly binds the two different metals avoiding the occurrence of any galvanic problem.



Material	Clad metal created through atomic diffusion
Bonding	method Atomic diffusion bonding (rolling process)
Heat resistance	Good thermal resistance No gas(no chemical adhesive)
Formability	Excellent bending formability
Corrosion resistance	No corrosion

► TUB 2000x500x1

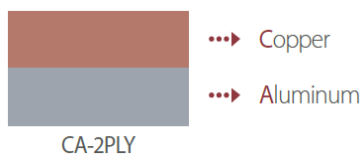
BIMETALLIC SHEET 70/30 CA-2PLY (Cu-Al)
Dimensions 2000x500x1 mm

Material Grade	Material Ratio	Thickness
Cu-ETP C1100	30%	0,30mm
Al 1050	70%	0,70mm
Density 4,58 kg/dm ³	Unit Weight 4,58 kg/pc	

► BIMETAL PLATES Cu-Al

Code		Holes	X	W	Thickness
Drilled	Undrilled	dimensions in mm			
TDB 30	TUB 30	P1	30	30	1
TDB 40	TUB 40	P1	40	40	1
TDB 50	TUB 50	P1	50	50	1
TDB 60	TUB 60	P1	60	60	1
TDB 80	TUB 80	P4	80	80	1
TDB 100	TUB 100	P5	100	100	1
TDB 120	TUB 120	P7	120	120	1

Special dimensions or executions on demand



Type	Composition of materials		Manufactured sizes (mm)	
			Thickness	Width
Copper + Aluminum	Clad Material	Cu 1020, 1100	0.5 ~ 4.0	≤580
	Base Material	Al 1050		

